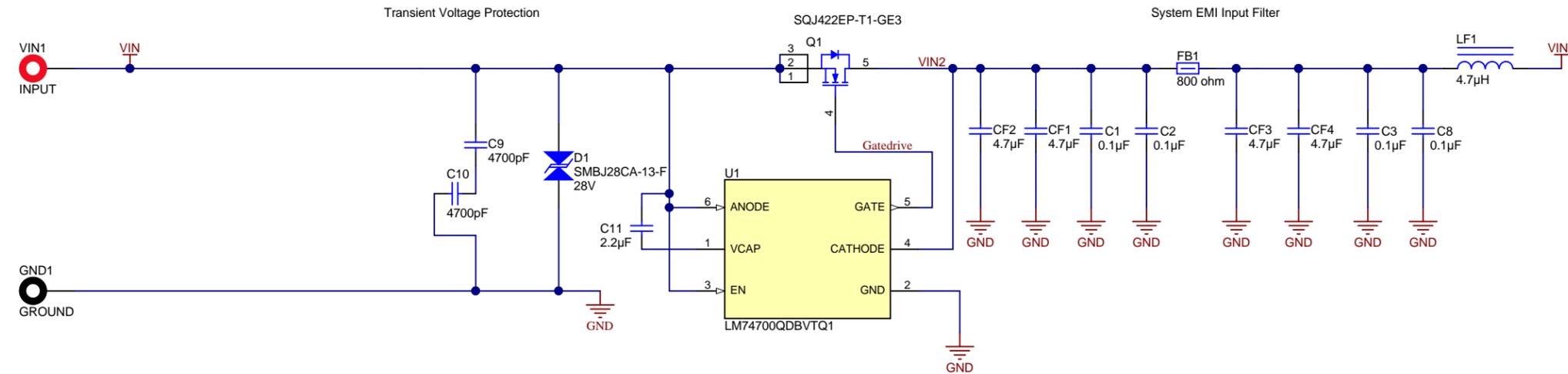


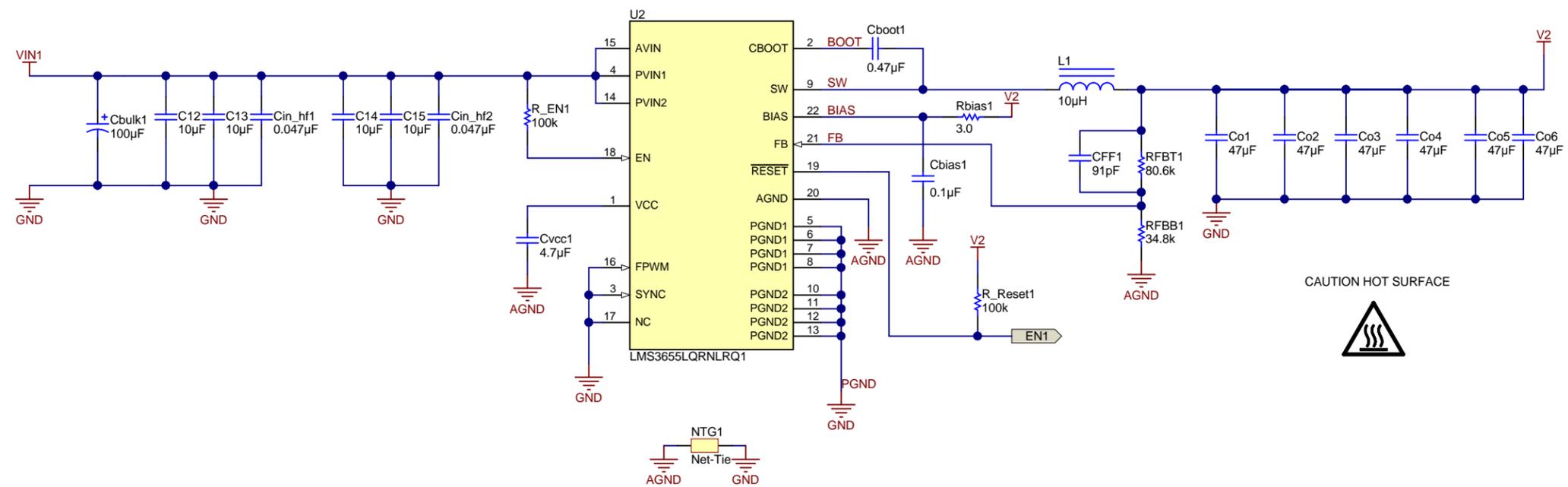
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| Drawn By: | File: TIDA-01524_CoverSheet_SchDoc | Size: B | |
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Reverse Battery Protection



3.3-V System Supply

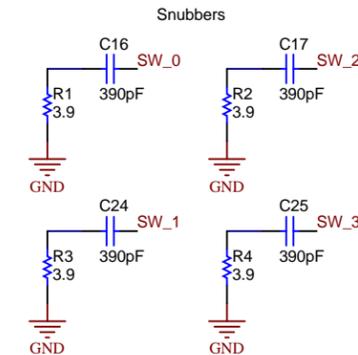
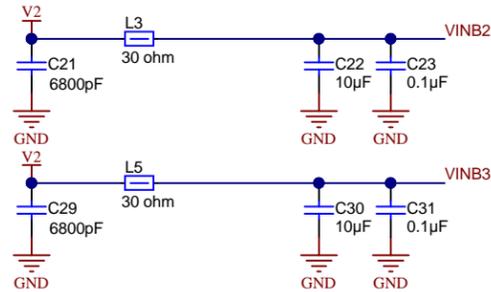
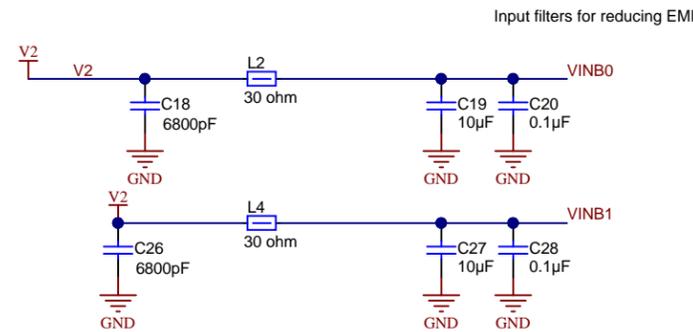


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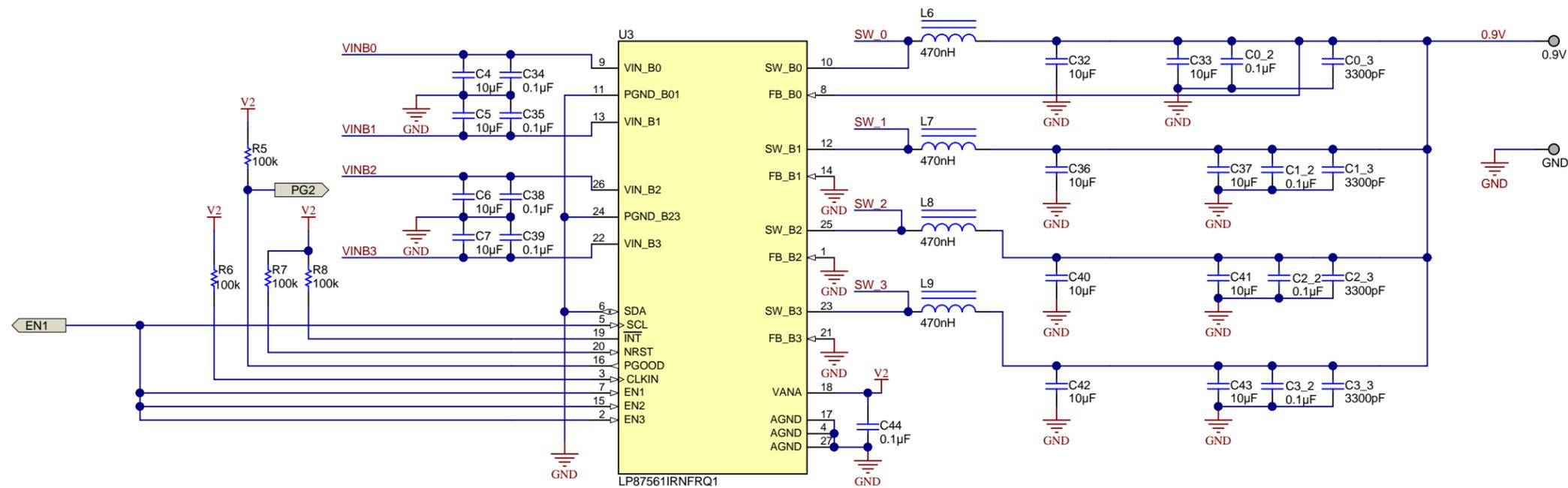
| | | |
|-----------------------------------|--|-----------------------|
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| TID #: TIDA-01524 | Project Title: High Efficiency Integrated Multi-Phase Processor S | |
| Number: TIDA-01524 | Rev: E1 | Sheet Title: |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 2 of 5 |
| Drawn By: | File: Main Supply + Smart Diode.SchDoc | Size: B |
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0.9-V Core-Voltage Supply



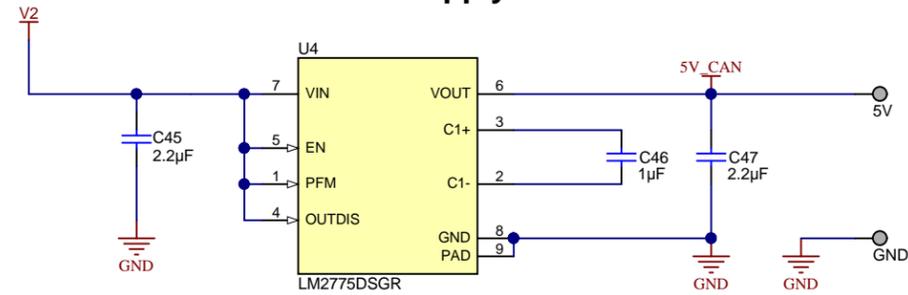
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| Number: TIDA-01524 | Rev: E1 | Sheet Title: |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 3 of 5 |
| Drawn By: | File: Core-Voltage Supply.SchDoc | Size: B |
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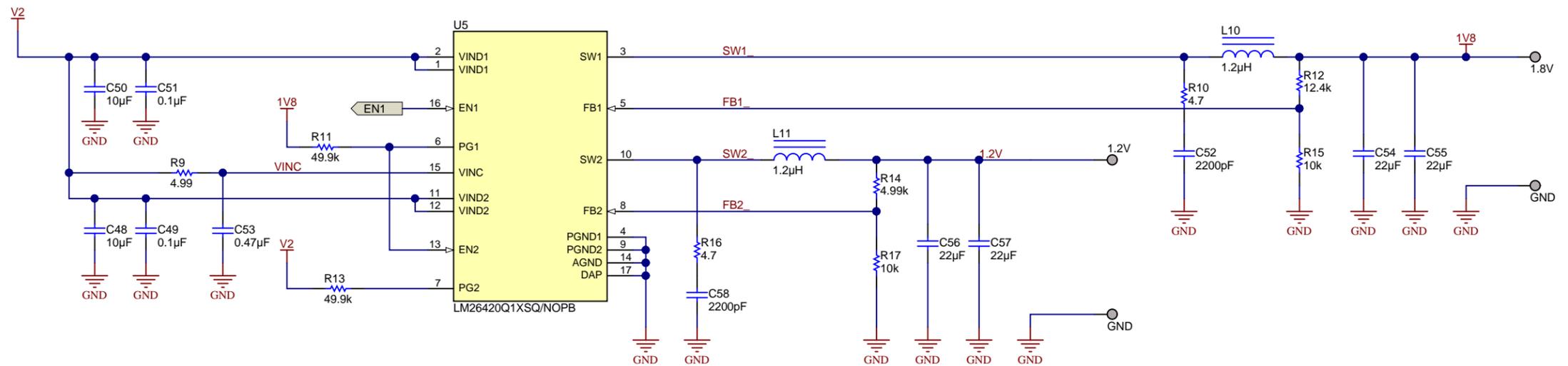


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5-V CAN Supply



Memory & IO Supplies



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| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 4 of 5 | |
| Drawn By: | File: Memory + IO + CAN Supply.SchDoc | Size: B | |
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PCB Number: TIDA-01524
PCB Rev: E1

PCB
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Pb-Free Symbol

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